

Amendments to the Claims

This listing of the claims will replace all prior versions, and listings, of claims in the application.

**Listing of Claims:**

Claim 1-9 (Canceled)

Claim 10 (Currently amended) A method for forming an improved field emission display device, comprising the steps of:

providing a screen; and

simultaneously applying a phosphor material and a binder material on said screen, said binder material holding said phosphor material to said screen, said binder material comprising a conductive material.

Claim 11-12 (Canceled)

Claim 13 (Currently amended) A method according to claim 10 wherein said binder material is selected from the group ~~including~~ consisting of: tin(II) 2-ethylhexanoate, tin (IV) isopropoxide, tin(II) oxalate, titanium (IV) ethoxide, zinc 2,4-pentane dionate, zinc acetate, and zinc oxalate.

Claim 14 (Currently amended) A method according to claim 10 wherein said binder material is selected from the group ~~including~~ consisting of: ~~poly(propylene carbonate)~~, poly(propylene carbonate) and poly(ethylene Carbonate).

Claim 15 (Currently amended) A method according to claim ~~[[10]]~~ 21 wherein said semiconductive binder material is selected from the group ~~including~~ consisting of: polyvinyl alcohol, potassium silicate, and ammonium silicate.

Claim 16 (Currently amended) A method according to claim 10 wherein the ~~glass~~ screen is coated with transparent conducting film selected from the group ~~including~~ consisting of: indium tin oxide (ITO), zinc oxide (ZnO), tin oxide (SnO<sub>2</sub>) doped with antimony (Sb), cadmium oxide (CdO), and cadmium tin oxide (Cadmium stannate) Cd<sub>2</sub>SnO<sub>4</sub>.

Claim 17 (Currently amended) A method according to claim 10 wherein the binder material is an ~~organometallic~~ organometallic compound selected from the group ~~including~~ consisting of: cadmium (Cd), titanium (Ti), zinc (Zn), tin (Sn), indium (In), antimony (Sb), tungsten (W), niobium (Nb), further comprising the step of heating said binder material to form conductive and/or semiconductive oxides.

Claim 18 (Original) A method according to claim 10 wherein said binder material is transparent.

Claim 19 (Currently amended) A method according to claim 10 wherein said binder material is heated to remove any organics and leave behind a conducting or semiconducting oxide which binds the phosphor particles to each other and to the ~~glass~~ screen.

Claim 20 (Currently amended) A method for forming a field emission display device, comprising:

- providing a faceplate comprising a transparent screen having at least one side;
- applying a transparent conductor to said side of said screen;
- simultaneously applying a layer of phosphor and conductive binder material to said transparent conductor, said binder material holding said phosphor to said transparent conductor;
- providing a baseplate comprising:
  - a base electrode;
  - a plurality of conical field emission cathodes having a base and a tip, the bases of said field emission cathodes being disposed on said base electrode; and
  - a grid electrode disposed ~~proximal~~ proximally to the tips of said field emission cathodes;
- positioning the baseplate proximal said side of said screen so that said baseplate is spaced apart from said faceplate; and
- providing a vacuum gap between said faceplate and said baseplate.

Claim 21 (Currently amended) A method for forming a field emission display device,  
comprising:

- providing a faceplate comprising a transparent screen having at least one side;
- applying a transparent conductor to said side of said screen;
- simultaneously applying a layer of phosphor and semiconductive binder material  
to said transparent conductor, said binder material holding said phosphor  
to said transparent conductor;

providing a baseplate comprising:

- a base electrode
- a plurality of conical field emission cathodes having a base and a tip, the  
bases of said field emission cathodes being disposed on said base  
electrode; and
- a grid electrode disposed ~~proximal~~ proximally to the tips of said  
field emission cathodes;

positioning the baseplate proximal said side of said screen so that said baseplate is  
spaced apart from said faceplate; and

providing a vacuum gap between said faceplate and said baseplate.